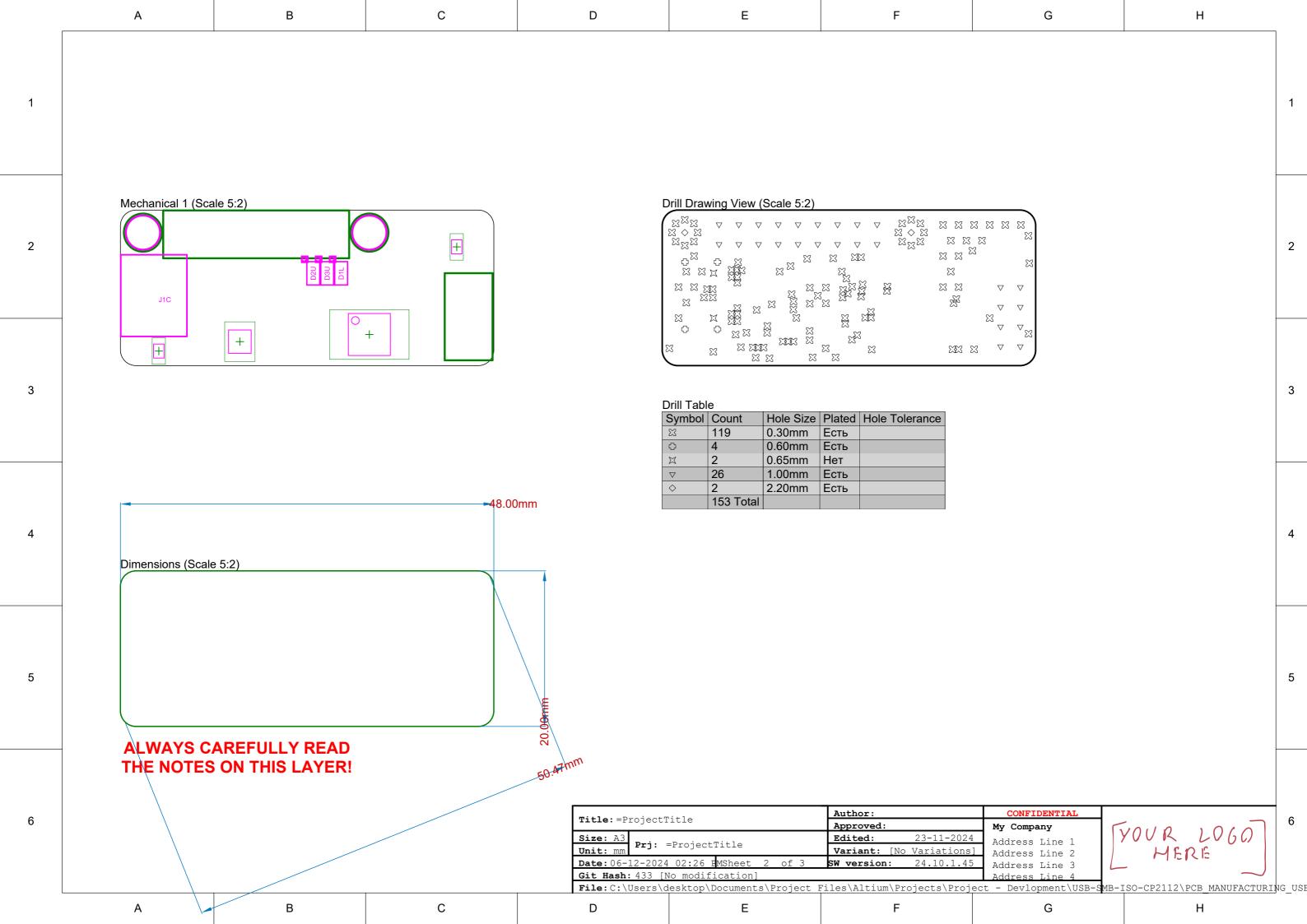
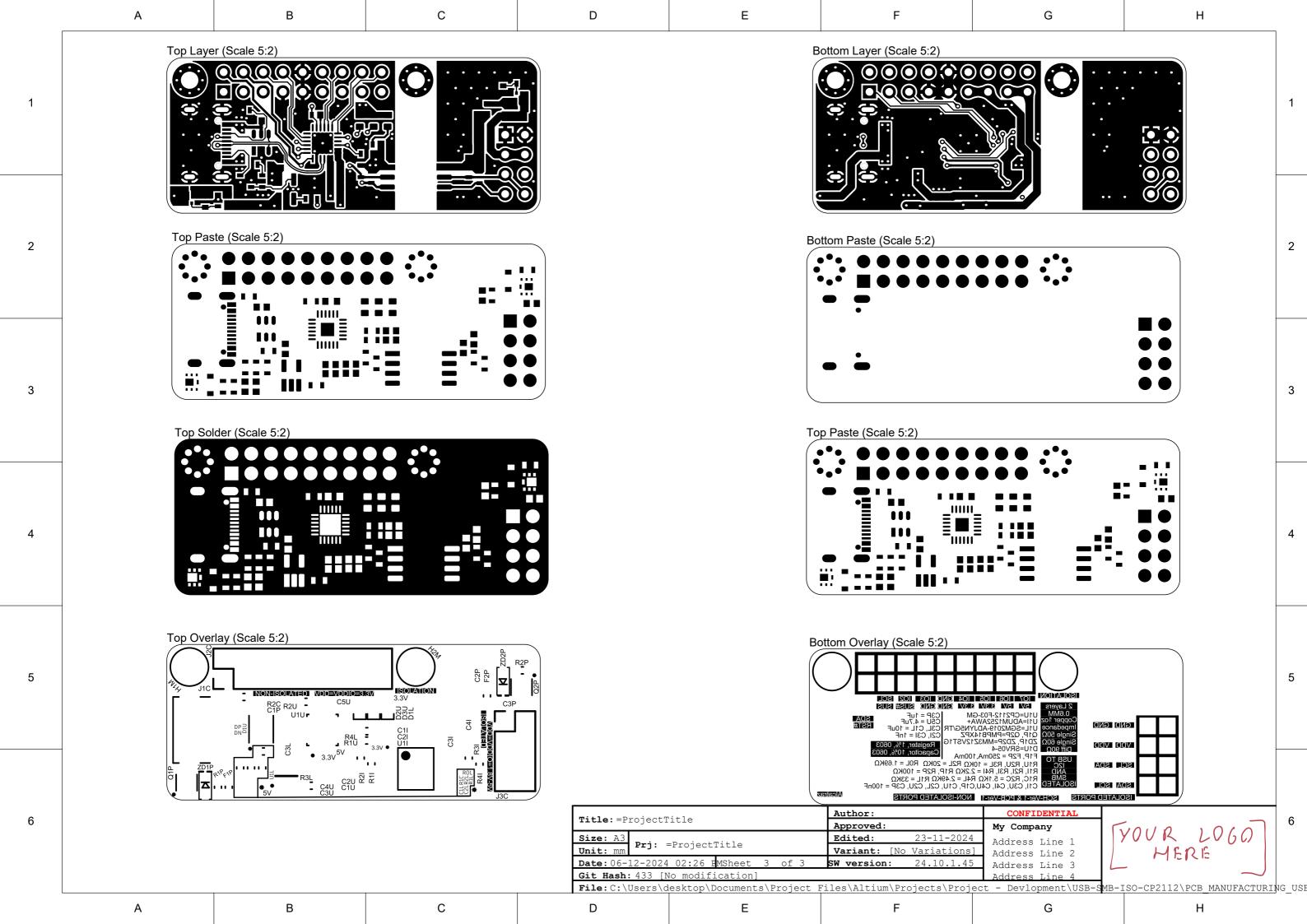
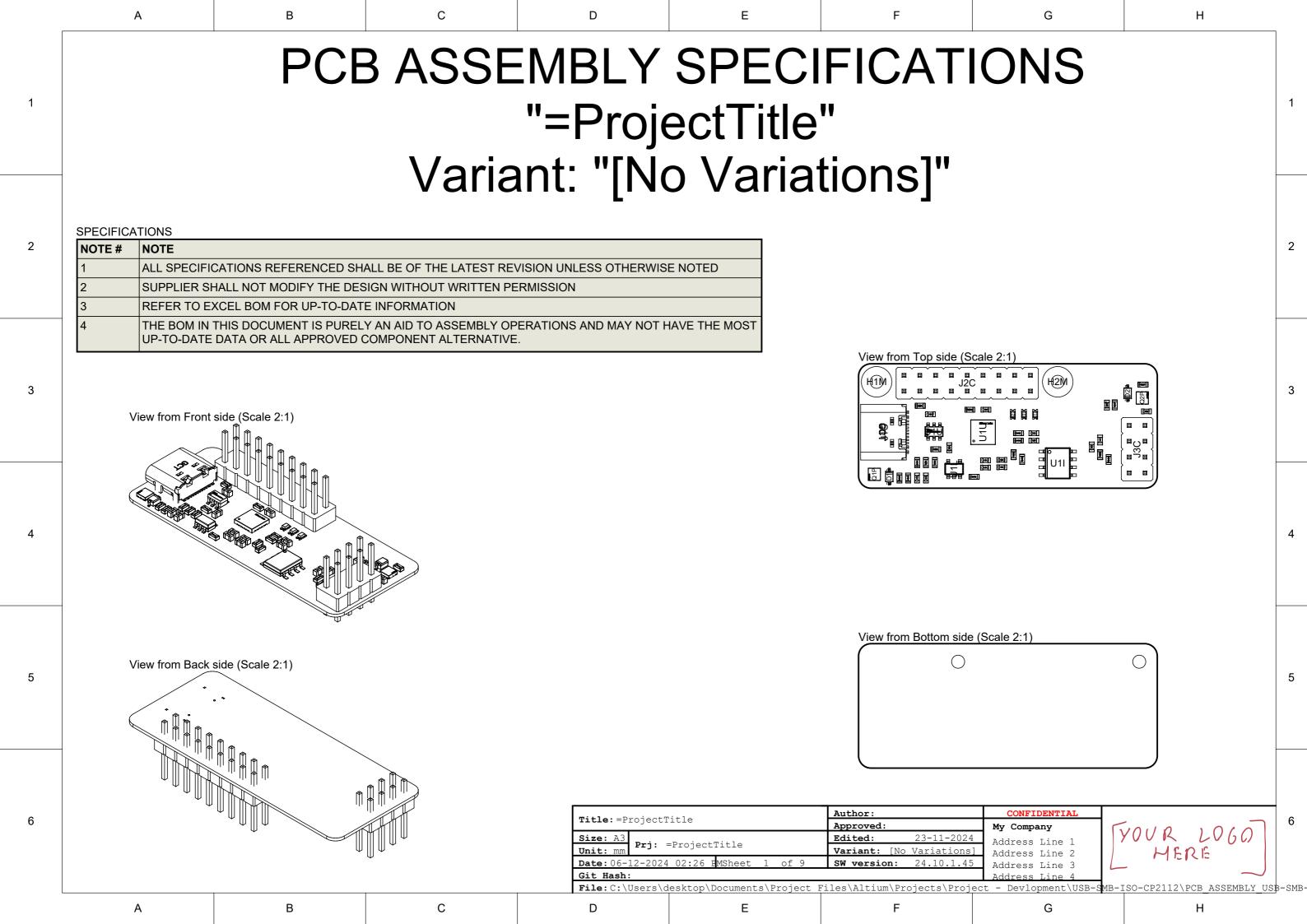
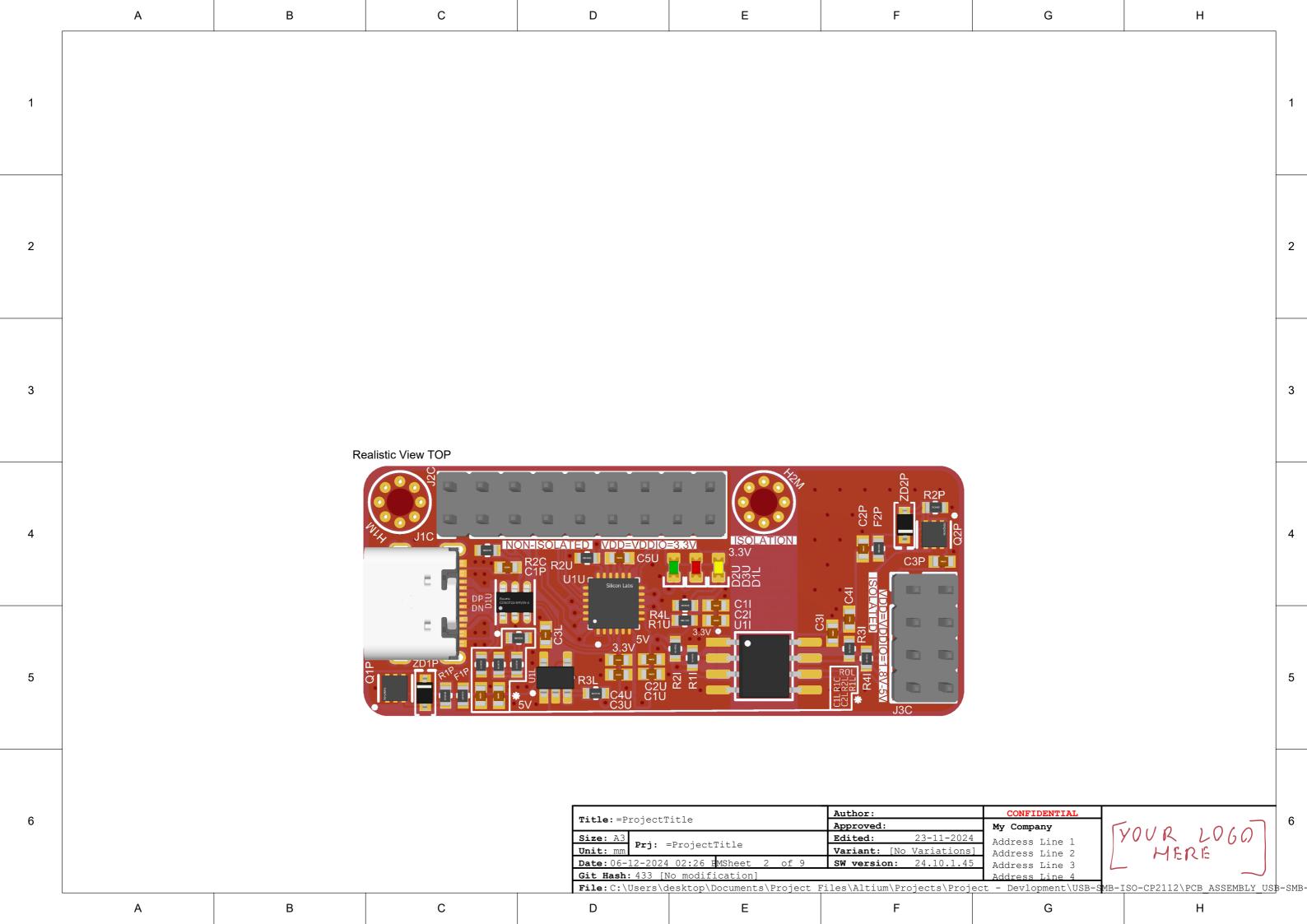


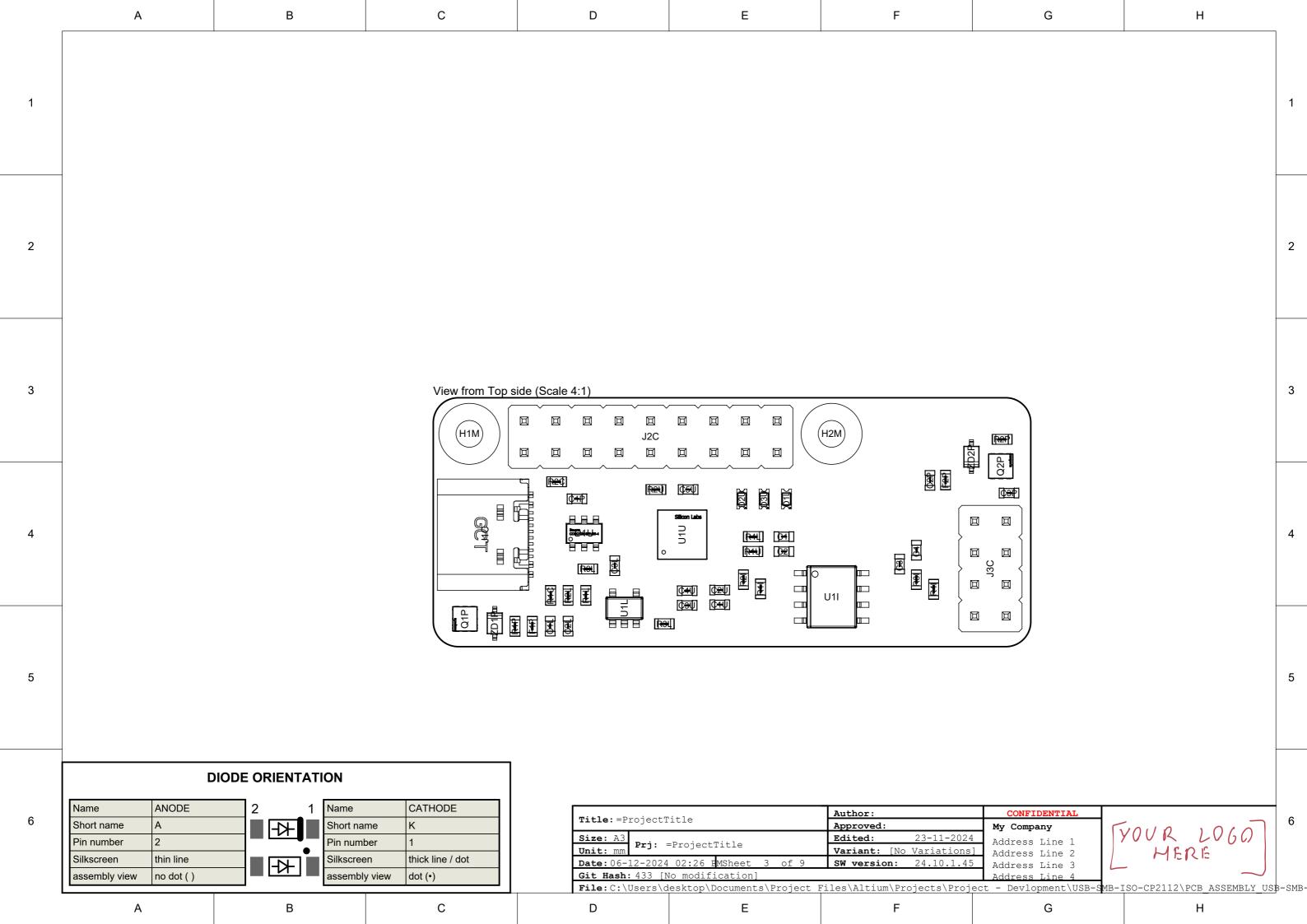
PCB MANUFACTURING SPECIFICATIONS "=ProjectTitle" **SPECIFICATIONS SPECIFICATIONS** NOTE# NOTE LENGHT 20.00mm **WIDTH** ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK 48.00mm **LAYERS** SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION FR-4 **MATERIAL** ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN RoHS ASSEMBLY. RoHS LOGO SHALL BE MARKED IN SILKSCREEN INK BY THE SUPPLIER WHERE INDICATED BY **MATERIAL MIN TG** 130-140 THE TEXT "PLACE MARKINGS HERE" TRACK WIDTH/CLEARANCE 10 mils / 10 mils COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE **THICKNESS** 0.6mm FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS **COPPER THICKNESS** 35um (1oz) ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-YES, TOP AND BOTTOM SOLDERMASK CONDUCTIVE. PERMANENT INK. **GREEN SOLDERMASK COLOR** MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE SILKSCREEN YES. TOP AND BOTTOM RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM NOTES" BY THE TEXT "PLACE MARKINGS SILKSCREEN COLOR WHITE MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS SURFACE FINISH **HASL LEAD FREE** OTHERWISE NOTED ONTO THE LAYER "PCBM NOTES" NO **GOLD FINGERS** SUPPLIER SHALL CHECK PCBM NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS **CHAMFERING** YES MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES YES IMPEDANCE CONTROL HALF-CUT/CASTELLATED HOLES NO **BURIED/BLIND VIAS** NO NO VIAS FILLED WITH RESIN Layer Stack Legend Material Layer Thickness Dielectric Material Type Gerber NO **CARBON MASK** Top Overlay GTO COUNTERSINKS/COUNTERBORES NO Surface Material Top Solder Solder Mask GTS NO **Z-AXIS MILLING** Copper Top Layer Signal GTL PEELABLE SOLDERMASK NO Core 0.50mm FR-4 Dielectric **GBL** 0.04mm Signal Solder Mask GBS Surface Material Bottom Solder 0.02mm Solder Resist GBO **Bottom Overlay** Legend Total thickness: 0.60mm NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE Author: Title: =ProjectTitle Approved: My Company Prj: =ProjectTitle Address Line 1 Variant: Address Line 2 Date: 06-12-2024 SW version: Address Line 3 С G В

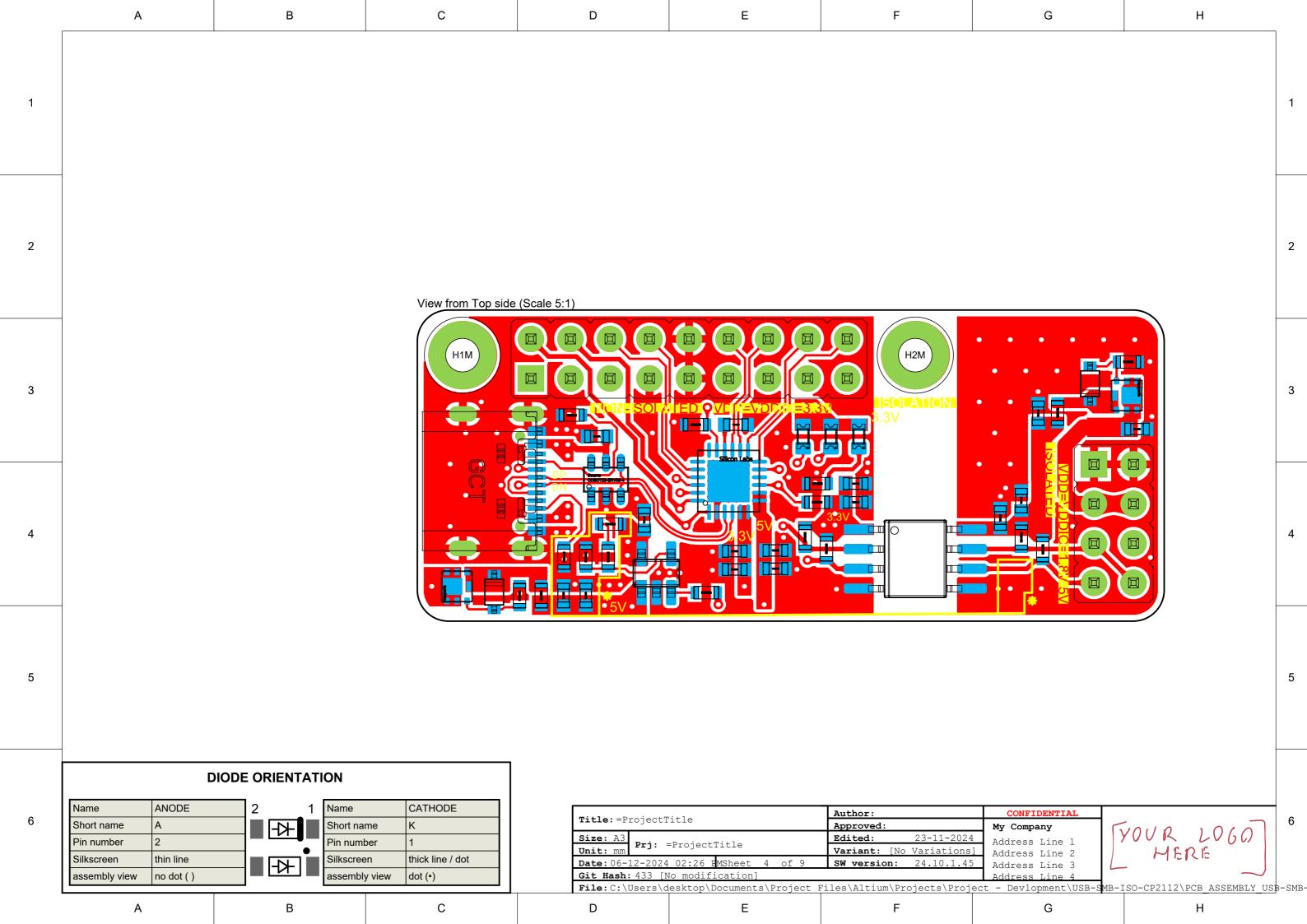


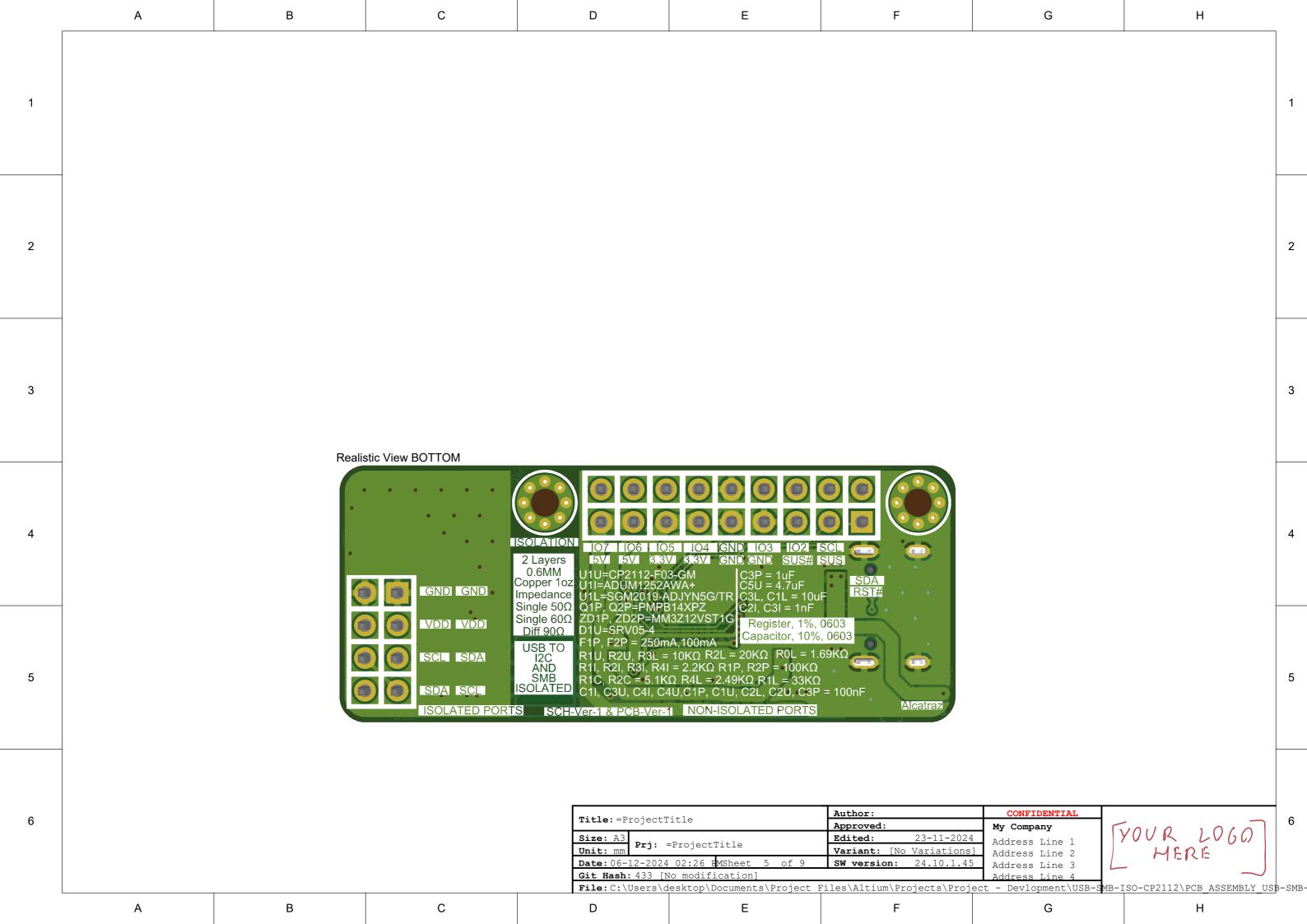


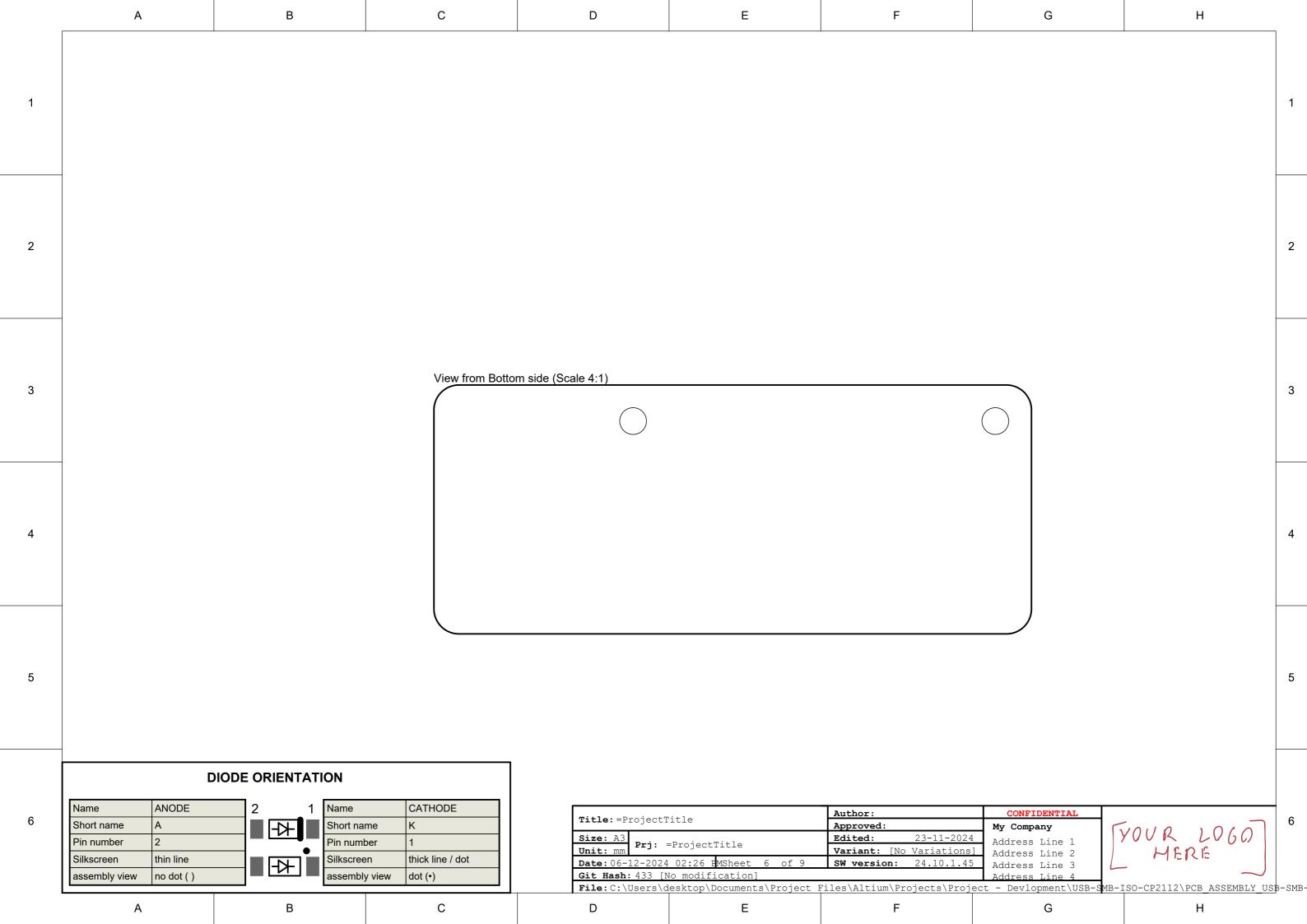


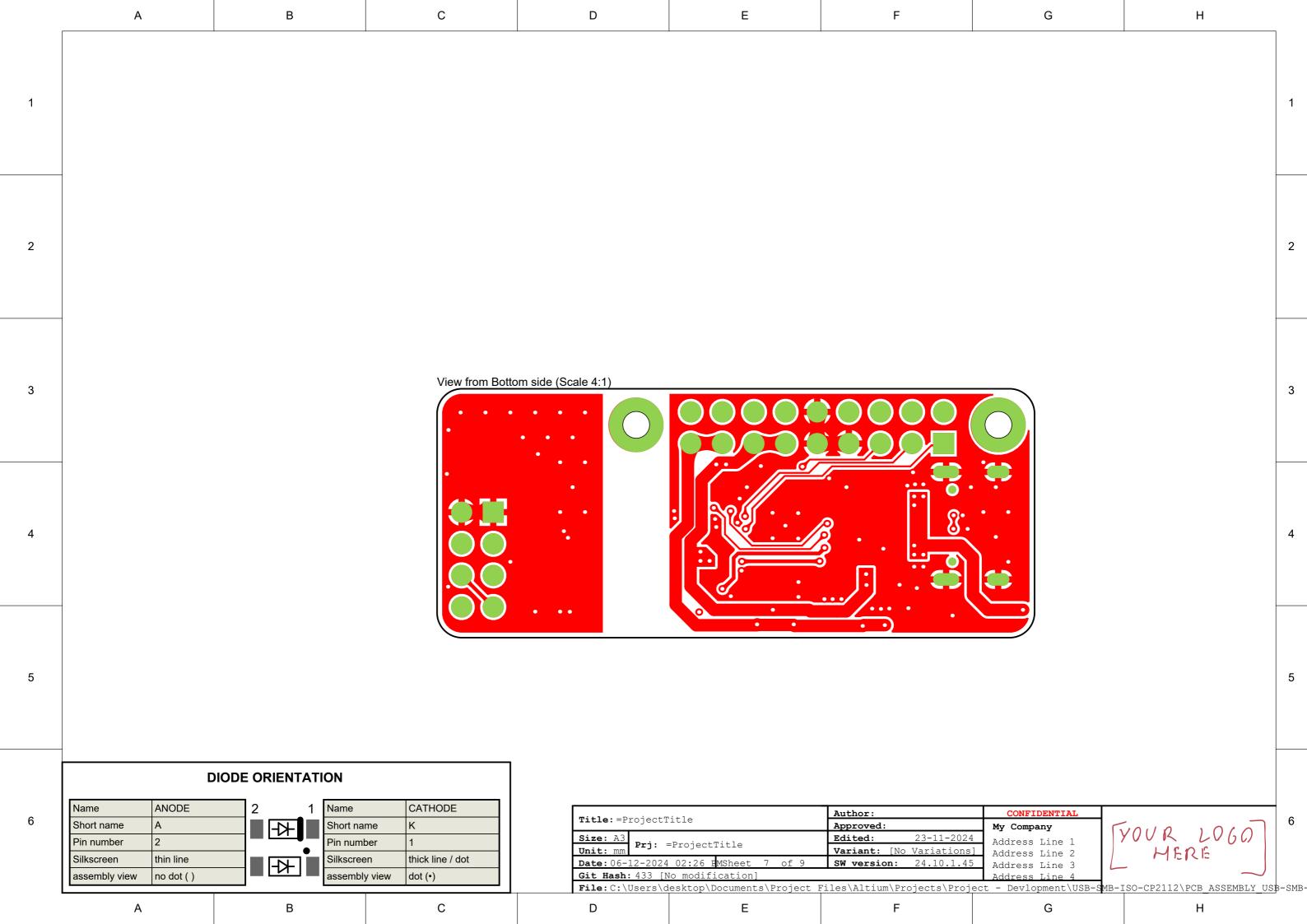


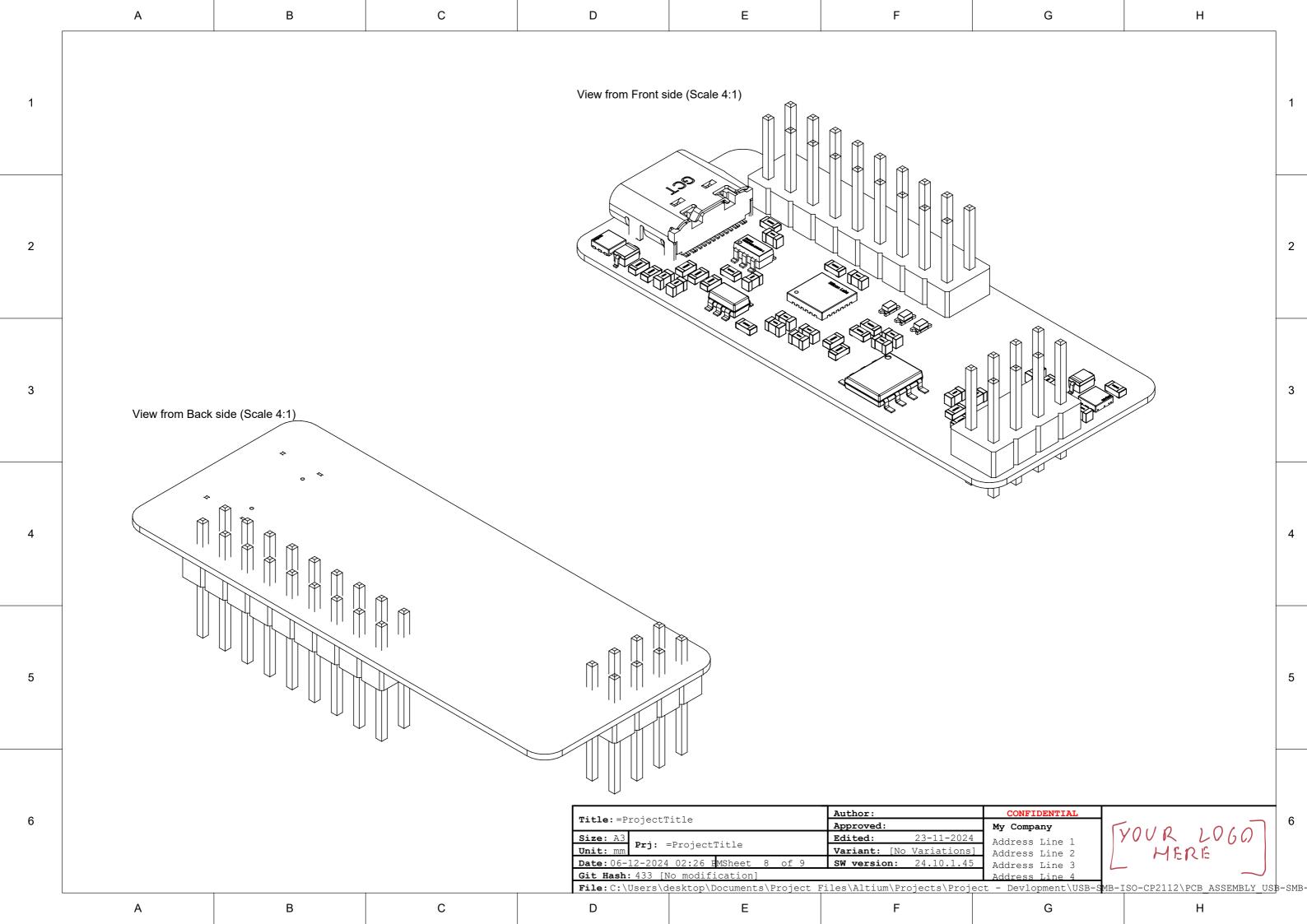












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	Bill Of M	atorials							
2	Line #	Description		Designator	Quantity	Manufacturer Part	Part Number	Layer	
	LIIIC #	Cap Cer 0.1UF 6.3V X7R 0603	3	C1I, C3U, C4		Number 1 KGM15AR70J104KM	T dit Number	Layor	2
		Multilayer Ceramic Capacitor, 10 uF, 10 V, ± 10%, X		C1L	1				
		Multilayer Ceramic Capacitor, 0.1 uF, 10 V, ± 10%, X7R, 0603 [1608 Metric]		C1P, C1U, C2L, C2U,	C3P, C4I 6	C0603C104K8RAC786			
		Cap Ceramic 0.001uF 6.3V C0G 10% SMD 0600 Ceramic Capacitor, Multilayer, Ceramic, 10V, 10% +Tol		C2I C2P	1	06036A102KAT2A			
3		1uF, 0603 Cap Ceramic 0.001uF 10V X7R 10% SMD 0603	3 125°C Paper T/R	C3I	1				
		Multilayer Ceramic Capacitor, 10 uF, 6.3 V, ± 10%, X Multilayer Ceramic Capacitor, 4.7 uF, 10 V, ± 10%, X	(5R, 0603 [1608 Metric]	C3L C5U	1	CL10A106KQ8NNNC CL10A475KP8NNNC			
		LED 0603 YELLOW SMD		D1L	1	CL TUA47 SKPOINING			
		TVS DIODE 5V 15V SOT23-6 LED 0603 GREEN SMD	6	D1U D2U	1				3
		LED 0603 GREEN SMD		D3U	1				
		Fuse PPTC SMD 0603 Fuse PPTC SMD 0603		F1P F2P	1				
		USB Connector Type C SMT 16 (Power pins joints = 12 pins)		J1C	1				
4				J2C J3C	1				
		PMPB14XPZ		Q1P, Q2P	2	PMPB14XPZ			
		Surface Mount Thick Film Chip Resistor 0603 Case 1.69 PPM	K Ohms 1% Tolerance 100	R0L	1	MCR03EZPFX1691			
		SMD Chip Resistor, 5.1 kOhm, ± 1%, 100 mW, 0603 [General Purpose		R1C, R2C	2	CRCW06035K10FKEA			4
		SMD Chip Resistor, 2.2 kOhm, ± 1%, 100 mW, 0603 [General Purpose	1608 Metric], Thick Film,	R1I, R2I, R3I, F	R4I 4	RC0603FR-072K2L			
		Res Thick Film 0603 33K Ohm 1% 0.1W(1/10W) ±100pp T/R		R1L	1	ERJ-3EKF3302V			
		SMD Chip Resistor, 100 kOhm, ± 1%, 100 mW, 0603 General Purpose		R1P, R2P	2	AC0603FR07100KL			
5		SMD Chip Resistor, 10 kOhm, ± 1%, 100 mW, 0603 [General Purpose	-	R1U, R2U, R3	3 3	RC0603FR-0710KL			
		SMD Chip Resistor, 20 kOhm, ± 1%, 100 mW, 0603 [General Purpose		R2L	1	CR0603-FX-2002ELF			
		Res Thick Film 0603 2.49K Ohm 1% 1/10W ±100ppm/°C T/R Ultra-Low Power, Bidirectional I2C Isolator with Extende		R4L	1				5
		and Low VOL	u voo, iuie-ous noi-swap	U1I	1	ADUM1252AWA+			
		LDO U-Reg Adj 0, 3A SOT23- IC HID USB-TO-SMBUS BRIDGE 2		U1L U1U	1	SGM2019-ADJYN5G/ TR			
		MM3Z12VST1G Zener Diode, 12V 2% 200 mW SM	T 2-Pin SOD-323 ON) 2				
6		Semiconductor MM3Z12VST1		ZD1P, ZD2P	2				
	Please consider LCSC (立创商城) as our first supplier BOM FOR REFERENCE ONLY			Title: =Project1	Title: =ProjectTitle		CONFIDENTIAL		<u> </u>
				Size: A3	Unit: mm Prj: =ProjectTitle		My Company 024 Address Line 1	YOUR LOGO HERE	$O \mid $
				Unit: mm Prj:			Address Line 2	MERE	
		REFERENCE ONLY REFER TO THE LATEST EXCEL BOM PRO	OVIDED		<pre>Date: 06-12-2024 02:26 FMSheet 9 of 9 Git Hash: 433 [No modification]</pre>		.45 Address Line 3 Address Line 4		\longrightarrow
					File: C:\Users\desktop\Documents\Project B			MB-ISO-CP2112\PCB_ASSEME	BLY_USB-SMB
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